

## 300mW, NPN Small Signal Transistor

### FEATURES

- AEC-Q101 qualified
- High current
- Low power loss, high efficiency
- Ideal for automated placement
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free

### APPLICATIONS

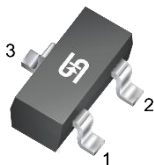
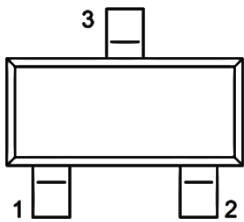
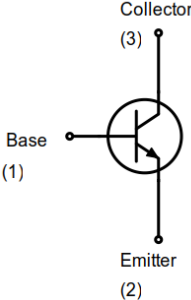
- General switching and amplification

### MECHANICAL DATA

- Case: SOT-23
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Weight: 8.00mg (approximately)



KEY PARAMETERS		
PARAMETER	VALUE	UNIT
$V_{CBO}$	50	V
$V_{CEO}$	45	V
$V_{EBO}$	5	V
$I_C$	500	mA
$h_{FE}$	400-600	
Configuration	Single die	

PACKAGE: SOT-23	PIN CONFIGURATION	CIRCUIT DIAGRAM
		

### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	VALUE	UNIT
Power dissipation <sup>(1)</sup>	$P_D$	300	mW
Collector-base voltage	$V_{CBO}$	50	V
Collector-emitter voltage	$V_{CEO}$	45	V
Emitter-base voltage	$V_{EBO}$	5	V
Collector current	$I_C$	500	mA
Junction temperature	$T_J$	-55 to +150	$^\circ\text{C}$
Storage temperature	$T_{STG}$	-55 to +150	$^\circ\text{C}$

#### Note:

1. Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint

<b>THERMAL PERFORMANCE</b>			
<b>PARAMETER</b>	<b>SYMBOL</b>	<b>TYP</b>	<b>UNIT</b>
Junction-to-ambient thermal resistance <sup>(1)</sup>	$R_{\theta JA}$	417	°C/W

**Thermal Performance Note:**

1. Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint

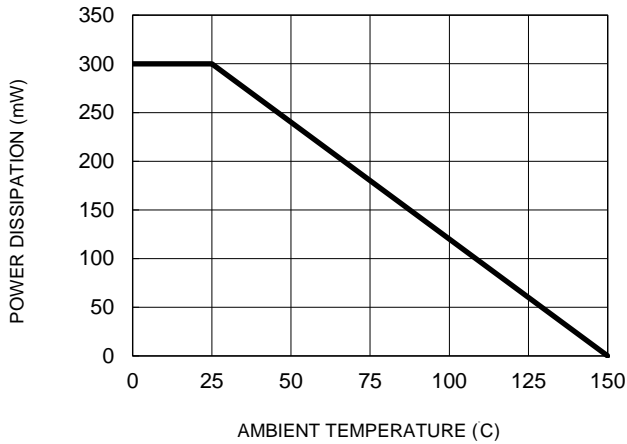
<b>ELECTRICAL SPECIFICATIONS</b> ( $T_A = 25^\circ\text{C}$ unless otherwise noted)							
<b>PARAMETER</b>	<b>CONDITIONS</b>		<b>SYMBOL</b>	<b>MIN</b>	<b>TYP</b>	<b>MAX</b>	<b>UNIT</b>
Collector-base breakdown voltage	$I_C = 10\mu\text{A}, I_E = 0\text{A}$		$V_{(BR)CBO}$	50	-	-	V
Collector-emitter breakdown voltage	$I_C = 10\text{mA}, I_B = 0\text{A}$		$V_{(BR)CEO}$	45	-	-	V
Emitter-base breakdown voltage	$I_E = 1\mu\text{A}, I_C = 0\text{A}$		$V_{(BR)EBO}$	5	-	-	V
Collector-base cut-off current	$V_{CB} = 45\text{V}, I_E = 0\text{A}$		$I_{CBO}$	-	-	0.1	$\mu\text{A}$
Emitter-base cut-off current	$V_{EB} = 4\text{V}, I_C = 0\text{A}$		$I_{EBO}$	-	-	0.1	$\mu\text{A}$
DC current gain	$V_{CE} = 1\text{V}, I_C = 100\text{mA}$	BC817-25H	$h_{FE}$	160	-	400	-
		BC817-40H		250	-	600	
	$V_{CE} = 1\text{V}, I_C = 500\text{mA}$			40	-	-	
Collector-emitter saturation voltage	$I_C = 500\text{mA}, I_B = 50\text{mA}$		$V_{CE(sat)}$	-	-	0.7	V
Base-emitter saturation voltage	$I_C = 500\text{mA}, I_B = 50\text{mA}$		$V_{BE(sat)}$	-	-	1.2	V
Base-emitter voltage	$V_{CE} = 1\text{V}, I_C = 500\text{mA}$		$V_{BE}$	-	-	1.2	V
Transition frequency	$V_{CE} = 5\text{V}, I_C = 10\text{mA}, f = 100\text{MHz}$		$f_T$	100	-	-	MHz
Output capacitance	$V_{CB} = 10\text{V}, I_E = 0\text{A}, f = 1\text{MHz}$		$C_{obo}$	-	5	-	pF

<b>ORDERING AND MARKING INFORMATION</b>			
<b>ORDERING CODE</b>	<b>PACKAGE</b>	<b>PACKING</b>	<b>DEVICE MARKING</b>
BC817-25H RFG	SOT-23	3,000 / 7" Tape & Reel	<u>6</u> B
BC817-40H RFG	SOT-23	3,000 / 7" Tape & Reel	<u>6</u> C

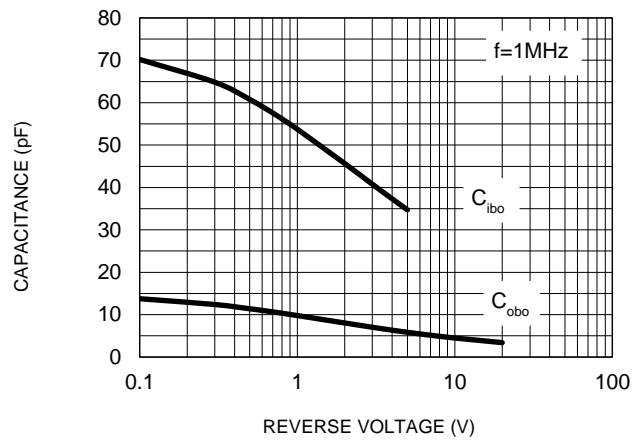
**CHARACTERISTICS CURVES**

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

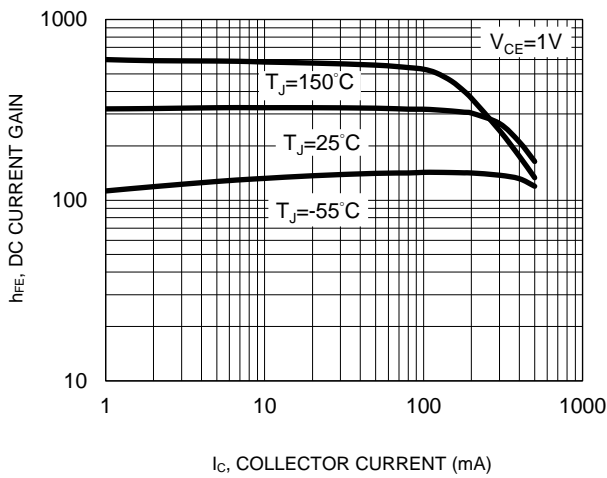
**Fig.1 Power Dissipation Curve**



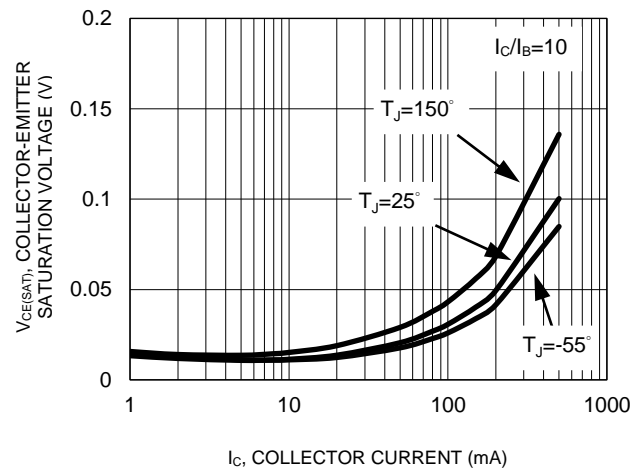
**Fig.2 Typical Capacitance Characteristics**



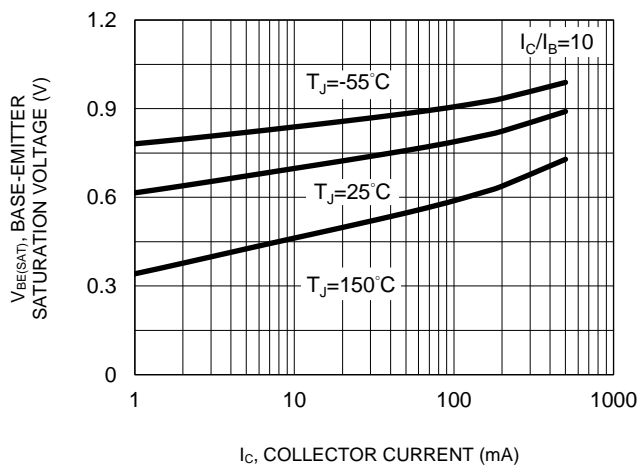
**Fig.3 DC Current Gain vs. Collector Current**



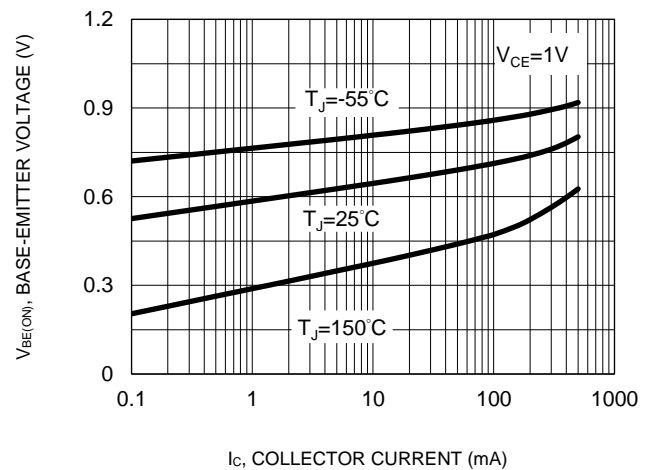
**Fig.4 Collector-Emitter Saturation Voltage vs. Collector Current**



**Fig.5 Base-Emitter Saturation Voltage vs. Collector Current**

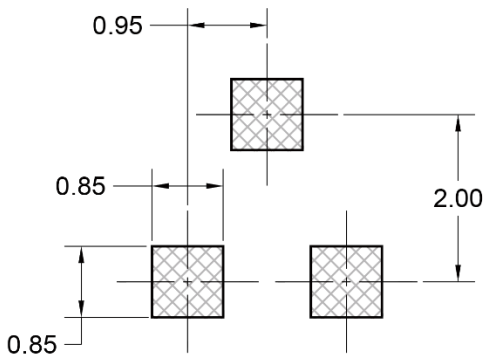
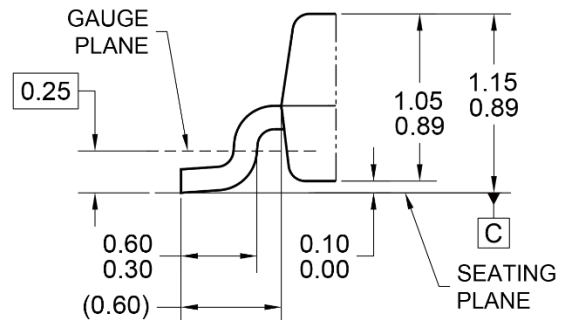
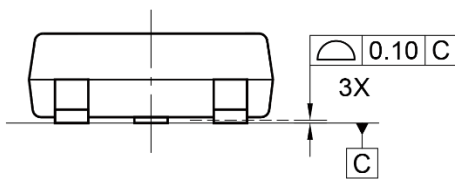
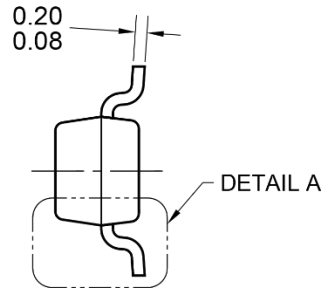
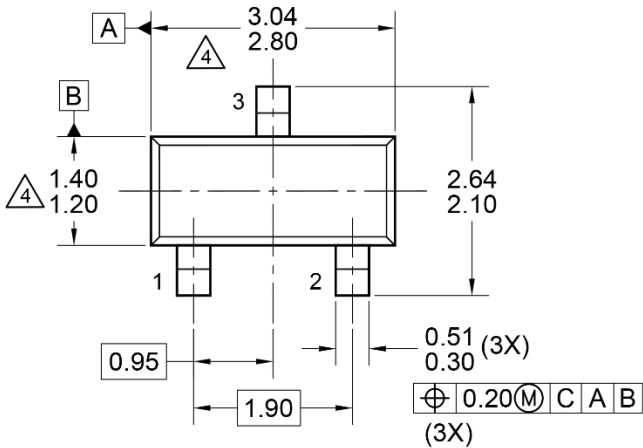


**Fig.6 Base-Emitter Voltage vs. Collector Current**

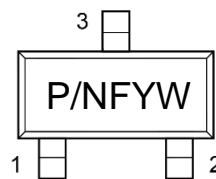


**PACKAGE OUTLINE DIMENSIONS**

**SOT-23**



**SUGGESTED PAD LAYOUT**



**MARKING DIAGRAM**

**NOTES: UNLESS OTHERWISE SPECIFIED**

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PACKAGE OUTLINE REFERENCE: JEDEC TO-236, ISSUE H, VARIATION AA.
4. MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
5. DWG NO. REF: HQ2SD07-SOT23JEDEC-104 REV B.

- P/N = Device marking  
 F = Factory code  
 Y = Year code  
 W = Bi-Week code (A~Z)

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